



BSS8402DW

COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Product Summary

Device	V _{(BR)DSS}	R _{DS(on) max}	I _D T _A = +25°C
Q1	60V	13.5Ω @ V _{GS} = 10V	115mA
Q2	-50V	10Ω @ V _{GS} = -5V	-130mA

Description

This MOSFET has been designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- General Purpose Interfacing Switch
- Power Management Functions
- Analog Switch

SOT363



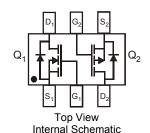
Top View

Features and Benefits

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- · Fast Switching Speed
- Low Input/Output Leakage
- Complementary Pair
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Weight: 0.006 grams (approximate)



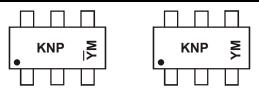
Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
BSS8402DW-7-F	Standard	SOT363	3,000/Tape & Reel
BSS8402DW-13-F	Standard	SOT363	10,000/Tape & Reel
BSS8402DWQ-7	Automotive	SOT363	3,000/Tape & Reel
BSS8402DWQ-13	Automotive	SOT363	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html

Marking Information



KNP = Product Type Marking Code

YM = Date Code Marking for SAT (Shanghai Assembly/ Test site)
YM = Date Code Marking for CAT (Chengdu Assembly/ Test site)

Y or \overline{Y} = Year (ex: A = 2013)

M = Month (ex: 9 = September)

Date Code Key

Date Code Ne	, y													
Year	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016
Code	Р	R	S	Т	U	V	W	X	Υ	Z	Α	В	С	D
Month	Jan	Feb	M	ar	Apr	May	Jun	Jul	Aug	Se	p	Oct	Nov	Dec
Code	1	2	(3	4	5	6	7	8	9)	0	Ν	D



Maximum Ratings - Total Device (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Power Dissipation (Note 5)	P_{D}	200	mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	625	°C/W
Operating and Storage Temperature Range	$T_{J_i} T_{STG}$	-55 to +150	°C

Maximum Ratings N-CHANNEL - Q₁, 2N7002 Section (@T_A = +25°C, unless otherwise specified.)

Characterist	Symbol	Value	Units	
Drain-Source Voltage	V _{DSS}	60	V	
Drain-Gate Voltage R _{GS} ≤ 1.0MΩ		V_{DGR}	60	V
Gate-Source Voltage	Continuous Pulsed	V_{GSS}	±20 ±40	V
Drain Current (Note 5)	Continuous Continuous @ +100°C Pulsed	I _D	115 73 800	mA

Maximum Ratings P-CHANNEL - Q₂, BSS84 Section (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Drain-Source Voltage		V _{DSS}	-50	V
Drain-Gate Voltage $R_{GS} \le 20K\Omega$		V_{DGR}	-50	V
Gate-Source Voltage	Continuous	V_{GSS}	±20	V
Drain Current (Note 5)	Continuous	I _D	-130	mA

Note:

^{5.} Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com.



Electrical Characteristics N-CHANNEL - Q₁, 2N7002 Section (@T_A = +25°C, unless otherwise specified.)

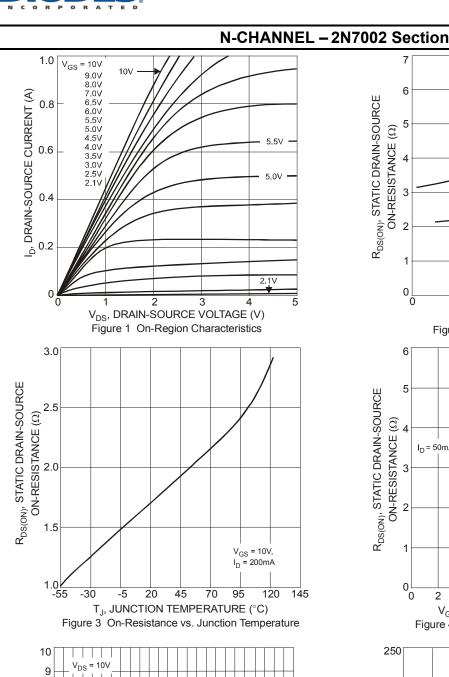
Characteristic			Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)							
Drain-Source Breakdown Voltage		BV _{DSS}	60	70	_	V	$V_{GS} = 0V$, $I_D = 10\mu A$
Zero Gate Voltage Drain Current	@ T _C = +25°C @ T _C = +125°C	I _{DSS}	_	_	1.0 500	μA	V _{DS} = 60V, V _{GS} = 0V
Gate-Body Leakage		I _{GSS}		_	±10	nA	V_{GS} = ±20V, V_{DS} = 0V
ON CHARACTERISTICS (Note 6)							
Gate Threshold Voltage		V _{GS(th)}	1.0	_	2.5	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
Static Drain-Source On-Resistance @ T _J = +25°C		J		3.2	7.5	5 Ω	$V_{GS} = 5.0V, I_D = 0.05A$
	@ $T_J = +125^{\circ}C$	R _{DS(on)}		4.4	13.5	12	V _{GS} = 10V, I _D = 0.5A
On-State Drain Current		I _{D(on)}	0.5	1.0	_	Α	V _{GS} = 10V, V _{DS} = 7.5V
Forward Transconductance		g _{FS}	80	—	_	mS	V _{DS} =10V, I _D = 0.2A
DYNAMIC CHARACTERISTICS							
Input Capacitance		C _{iss}		22	50	pF	
Output Capacitance		Coss	_	11	25	pF	$V_{DS} = 25V$, $V_{GS} = 0V$, $f = 1.0MHz$
Reverse Transfer Capacitance		C _{rss}	_	2.0	5.0	pF	
SWITCHING CHARACTERISTICS							
Turn-On Delay Time		t _{D(on)}	_	7.0	20	ns	V _{DD} = 30V, I _D = 0.2A,
Turn-Off Delay Time		t _{D(off)}	_	11	20	ns	$R_L = 150\Omega$, $V_{GEN} = 10V$, $R_{GEN} = 25\Omega$

Electrical Characteristics P-CHANNEL - Q₂, BSS84 Section (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 6)		I	I		•		
Drain-Source Breakdown Voltage	BV _{DSS}	-50	_	_	V	V _{GS} = 0V, I _D = -250μA	
Zero Gate Voltage Drain Current	I _{DSS}			-1 -2 -100	μΑ μΑ nA	V _{DS} = -50V, V _{GS} = 0V, T _J = 25°C V _{DS} = -50V, V _{GS} = 0V, T _J = 125°C V _{DS} = -25V, V _{GS} = 0V, T _J = 25°C	
Gate-Body Leakage	I _{GSS}	_	_	±10	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 6)							
Gate Threshold Voltage	V _{GS(th)}	-0.8	_	-2.0	V	$V_{DS} = V_{GS}$, $I_D = -1mA$	
Static Drain-Source On-Resistance	R _{DS (on)}	_	_	10	Ω	$V_{GS} = -5V, I_D = -0.100A$	
Forward Transconductance	9 FS	.05	_	_	S	$V_{DS} = -25V, I_{D} = -0.1A$	
DYNAMIC CHARACTERISTICS							
Input Capacitance	C _{iss}	_	_	45	pF		
Output Capacitance	Coss	_	_	25	pF	$V_{DS} = -25V, V_{GS} = 0V, f = 1.0MHz$	
Reverse Transfer Capacitance	C _{rss}	_	_	12	pF		
SWITCHING CHARACTERISTICS							
Turn-On Delay Time	t _{D(on)}	_	10	_	ns	$V_{DD} = -30V, I_D = -0.27A,$	
Turn-Off Delay Time	t _{D(off)}	_	18	_	ns	$R_{GEN} = 50\Omega$, $V_{GS} = -10V$	

Note: 6. Short duration pulse test used to minimize self-heating effect.





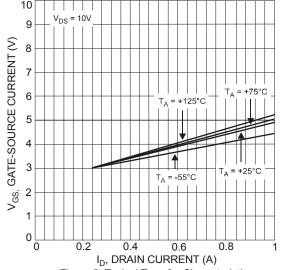
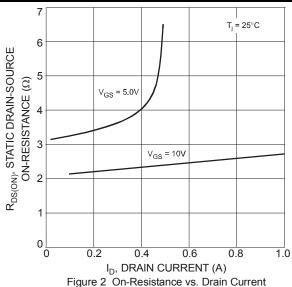


Figure 5 Typical Transfer Characteristics



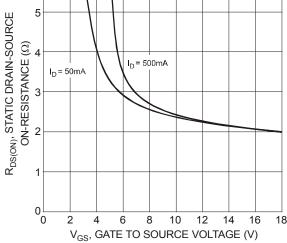


Figure 4 On-Resistance vs. Gate-Source Voltage

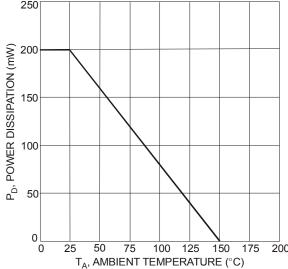
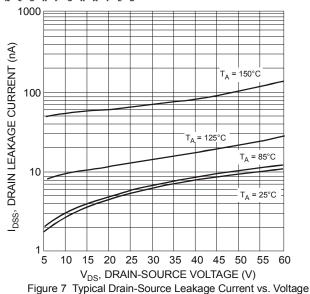
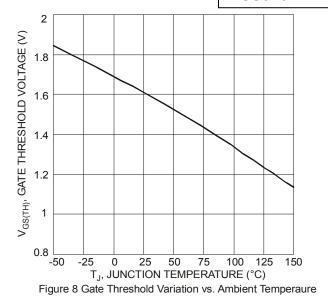


Figure 6 Max Power Dissipation vs. Ambient Temperature



BSS8402DW





P-CHANNEL - BSS84 Section

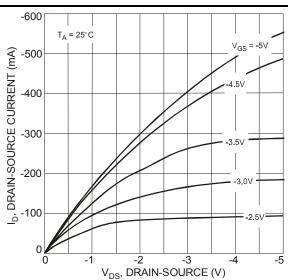


Figure 9 Drain-Source Current vs. Drain-Source Voltage

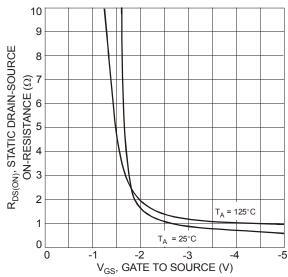
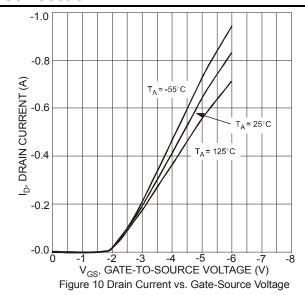


Figure 11 On-Resistance vs. Gate-Source Voltage



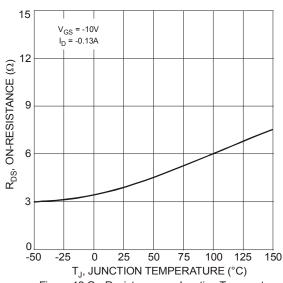
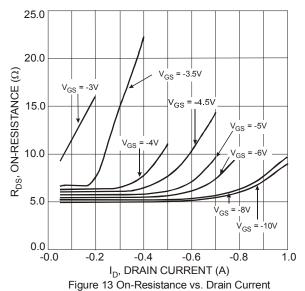
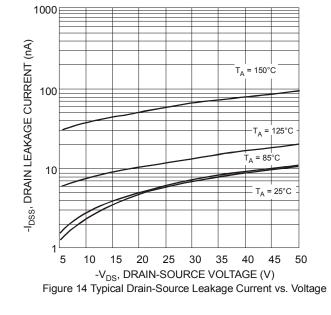


Figure 12 On-Resistance vs. Junction Temperature







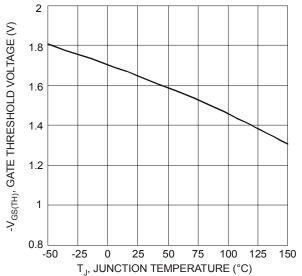
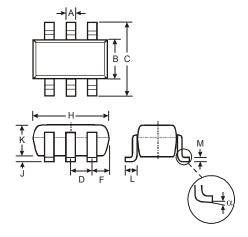


Figure 15 Gate Threshold Variation vs. Ambient Temperaure

Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

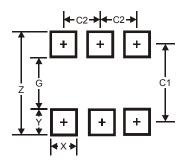


	SOT363						
Dim	Min	Max	Тур				
Α	0.10	0.30	0.25				
В	1.15	1.35	1.30				
С	2.00	2.20	2.10				
D		0.65 Ty	p				
F	0.40	0.45	0.425				
Н	1.80	2.20	2.15				
7	0	0.10	0.05				
K	0.90	1.00	1.00				
L	0.25	0.40	0.30				
М	0.10	0.22	0.11				
α	0°	8°	-				
All	Dimen	sions i	n mm				



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Υ	0.6
C1	1.9
C2	0.65

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